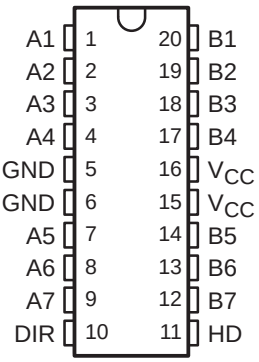
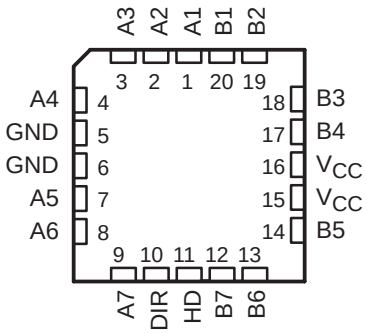
- **4.5-V to 5.5-V V_{CC} Operation**
- **Inputs Accept Voltages to 5.5 V**
- **Max t_{pd} of 20 ns at 5 V**
- **3-State Outputs Directly Drive Bus Lines**
- **Flow-Through Architecture Optimizes PCB Layout**
- **Center-Pin V_{CC} and GND Configurations Minimize High-Speed Switching Noise**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **200-V Machine Model (A115-A)**
- **Designed for the IEEE 1284-I (Level-1 Type) and IEEE 1284-II (Level-2 Type) Electrical Specifications**

SN54ACT1284 . . . J OR W PACKAGE
SN74ACT1284 . . . DB, DW, NS, OR PW PACKAGE
(TOP VIEW)



SN54ACT1284 . . . FK PACKAGE
(TOP VIEW)



description/ordering information

The ’ACT1284 devices are designed for asynchronous two-way communication between data buses. The control function minimizes external timing requirements.

The devices allow data transmission in either the A-to-B or the B-to-A direction for bits 1, 2, 3, and 4, depending on the logic level at the direction-control (DIR) input. Bits 5, 6, and 7, however, always transmit in the A-to-B direction.

The output drive for each mode is determined by the high-drive (HD) control pin. When HD is high, the high drive is delivered by the totem-pole configuration, and when HD is low, the outputs are open drain. This meets the drive requirements as specified in the IEEE 1284-I (level-1 type) and the IEEE 1284-II (level-2 type) parallel peripheral-interface specification.

ORDERING INFORMATION

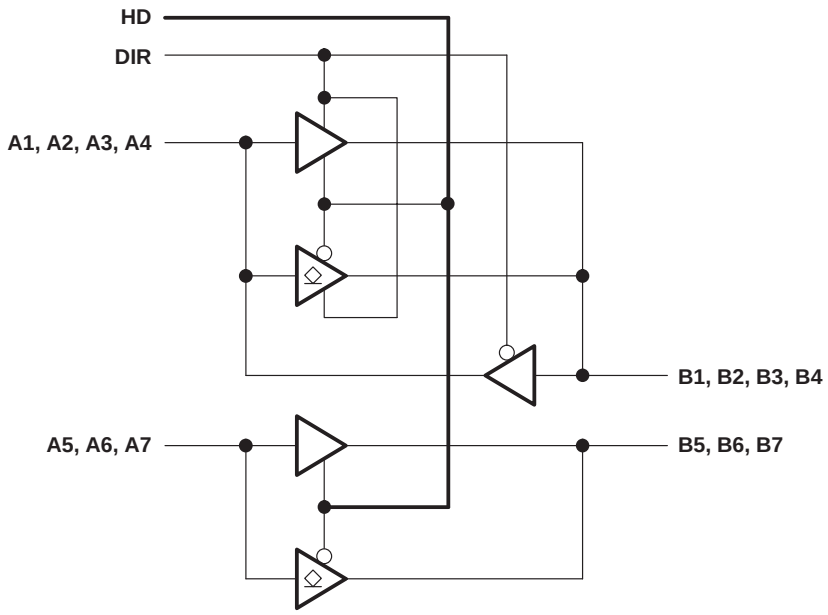
T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	SOIC − DW	Tube	SN74ACT1284DW	ACT1284
		Tape and reel	SN74ACT1284DWR	
	SOP − NS	Tape and reel	SN74ACT1284NSR	ACT1284
	SSOP − DB	Tape and reel	SN74ACT1284DBR	AU284
	TSSOP − PW	Tube	SN74ACT1284PW	AU284
		Tape and reel	SN74ACT1284PWR	
−55°C to 125°C	CDIP − J	Tube	SNJ54ACT1284J	SNJ54ACT1284J
	CFP − W	Tube	SNJ54ACT1284W	SNJ54ACT1284W
	LCCC − FK	Tube	SNJ54ACT1284FK	SNJ54ACT1284FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUTS		OUTPUT	MODE
DIR	HD		
L	L	Open drain	A to B: Bits 5, 6, 7
		Totem pole	B to A: Bits 1, 2, 3, 4
L	H	Totem pole	B to A: Bits 1, 2, 3, 4 and A to B: Bits 5, 6, 7
H	L	Open drain	A to B: Bits 1, 2, 3, 4, 5, 6, 7
H	H	Totem pole	A to B: Bits 1, 2, 3, 4, 5, 6, 7

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . −0.5 V to 7 V
B-port input and output voltage range, V_I and V_O (see Notes 1 and 2) . . . . . −2 V to 7 V
A-port input and output voltage range, V_I and V_O (see Note 1) . . . . . −0.5 V to V_{CC} + 0.5 V
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{CC}) . . . . . ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{CC}) . . . . . ±50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) . . . . . ±50 mA
Continuous current through V_{CC} or GND . . . . . ±200 mA
Package thermal impedance, θ_{JA} (see Note 3): DB package . . . . . 70°C/W
DW package . . . . . 58°C/W
NS package . . . . . 60°C/W
PW package . . . . . 83°C/W
Storage temperature range, T_{stg} . . . . . −65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The ac input voltage pulse duration is limited to 20 ns if the input voltage goes more negative than −0.5 V.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

			SN54ACT1284		SN74ACT1284		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.7	5.5	4.7	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
V_O	Open-drain output voltage	HD low	0	5.5	0	5.5	V
I_{OH}	High-level output current	B port, HD high		−14		−14	mA
		A port		−4		−4	
I_{OL}	Low-level output current	B port		14		14	mA
		A port		4		4	
T_A	Operating free-air temperature		−55	125	0	70	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended ranges of operating free-air temperature and supply voltage (unless otherwise noted)

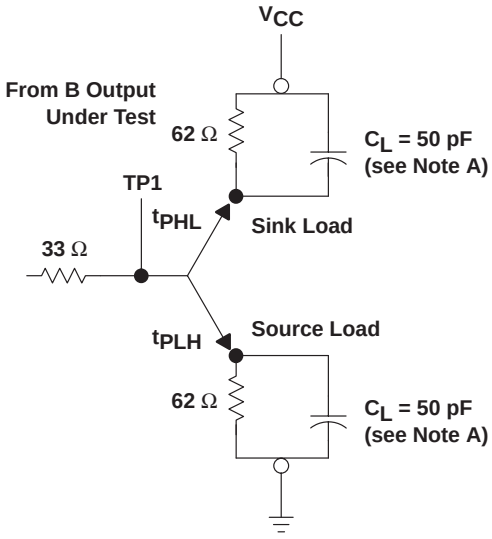
PARAMETER		TEST CONDITIONS	V_{CC}†	SN54ACT1284			SN74ACT1284			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
V_{hys}	Input hysteresis	$V_{IT+} - V_{IT-}$ for all inputs	5 V	0.4			0.4			V
			4.7 V	0.2			0.2			
V_{OH}	B port	I_{OH} = −14 mA	4.7 V	2.4			2.4			V
	A port	I_{OH} = −50 µA	MIN to MAX	V_{CC}−0.2			V_{CC}−0.2			
		I_{OH} = −4 mA	4.7 V	3.7			3.7			
V_{OL}	B port	I_{OL} = 14 mA	4.7 V			0.4			0.4	V
	A port	I_{OL} = 50 µA				0.2			0.2	
		I_{OL} = 4 mA				0.4			0.4	
I_I		$V_I = V_{CC}$ or GND	5.5 V			±1			±1	µA
I_{OZ}	A or B ports‡	$V_O = V_{CC}$ or GND	5.5 V			±20			±20	µA
I_{off}	B port	V_I or $V_O \le 7$ V	0 V			±100			±100	µA
I_{CC}		$V_I = V_{CC}$ or GND, I_O = 0	5.5 V			1.5			1.5	mA
C_i	Control inputs	$V_I = V_{CC}$ or GND	5 V		4			4		pF
C_{io}	A or B ports	$V_O = V_{CC}$ or GND	5 V		12			12		pF
Z_O	B port	I_{OH} = −20 mA, I_{OH} = −50 mA	5 V	8		30	8		30	Ω

† For I/O ports, the parameter I_{OZ} includes the input leakage current I_I.
‡ For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

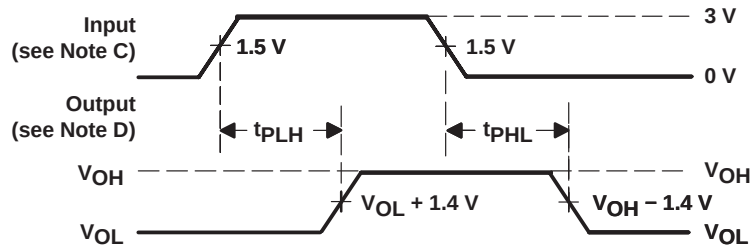
switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	SN54ACT1284		SN74ACT1284		UNIT
				MIN	MAX	MIN	MAX	
t_{PLH}	Totem pole	A or B	B or A	1	20	1	20	ns
t_{PHL}				1	20	1	20	
SR	Totem pole	B output		0.05	0.4	0.05	0.4	V/ns
t_{pd}(EN)	Totem pole	HD	B	1	20	1	20	ns
t_{pd}(DIS)				1	20	1	20	
t_r, t_f	Open drain	A	B		120		120	ns

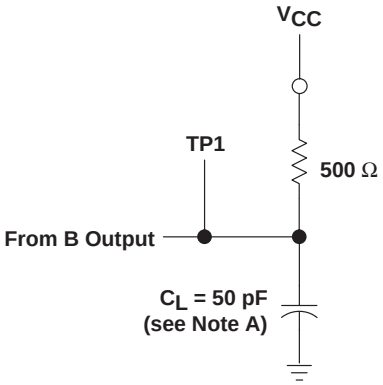
PARAMETER MEASUREMENT INFORMATION



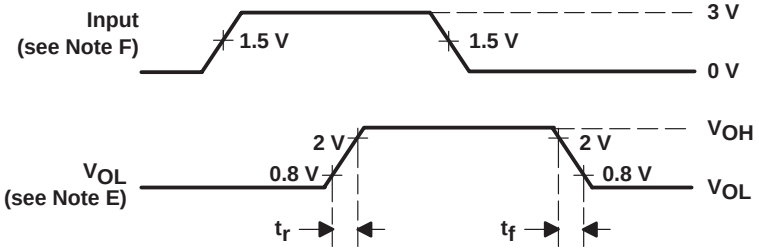
A-TO-B LOAD (totem pole)



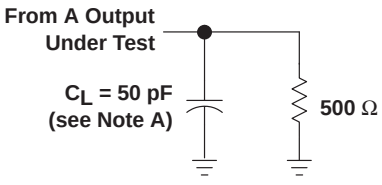
VOLTAGE WAVEFORMS MEASURED AT TP1
PROPAGATION DELAY TIMES (A to B)



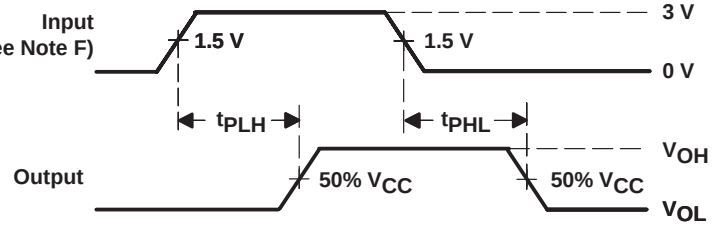
A-TO-B LOAD (open drain)



VOLTAGE WAVEFORMS MEASURED AT TP1 (B SIDE)



B-TO-A LOAD (totem pole)



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES (B to A)

NOTES: A. CL includes probe and jig capacitance.
B. The outputs are measured one at a time with one transition per measurement.
C. Input rise and fall times are 3 ns, 150 ns < pulse duration <10 μs for both low-to-high and high-to-low transitions.
D. Slew rate is defined as 10% and 90% of the transition times.
E. Rise and fall times, open drain, are <120 ns.
F. Input rise and fall times are 3 ns.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ACT1284DBR	ACTIVE	SSOP	DB	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	AU284	Samples
SN74ACT1284DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ACT1284	Samples
SN74ACT1284DWR	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ACT1284	Samples
SN74ACT1284NSR	ACTIVE	SOP	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ACT1284	Samples
SN74ACT1284PWR	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	AU284	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

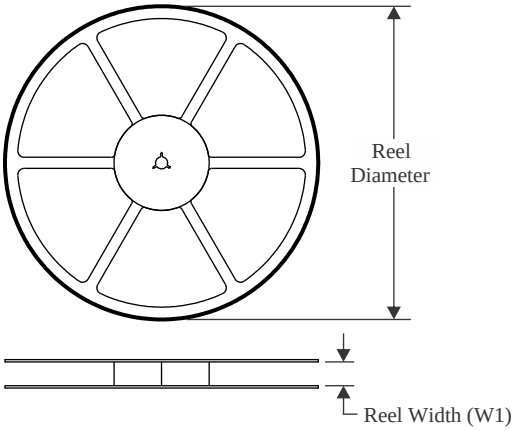
(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

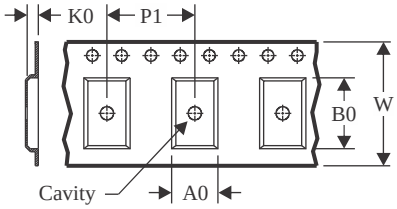
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

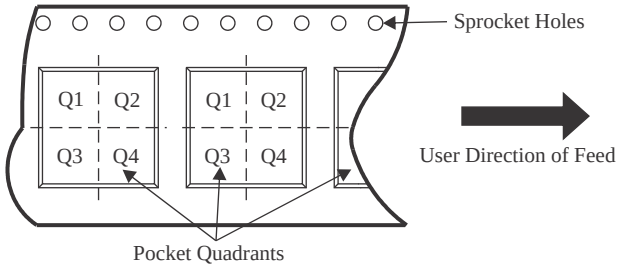


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

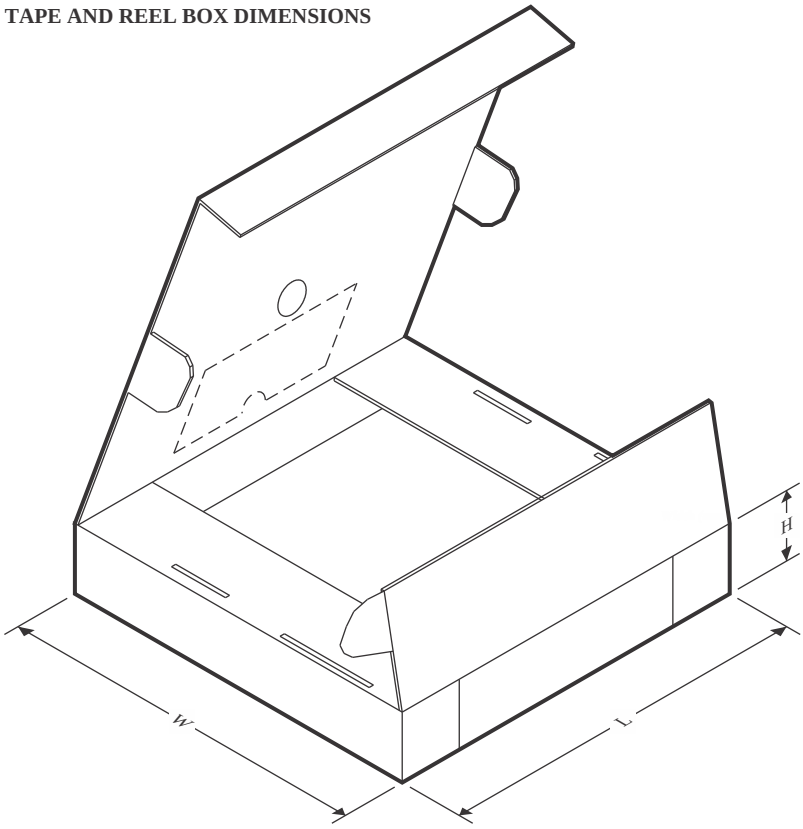
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ACT1284DBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ACT1284DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ACT1284NSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74ACT1284PWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

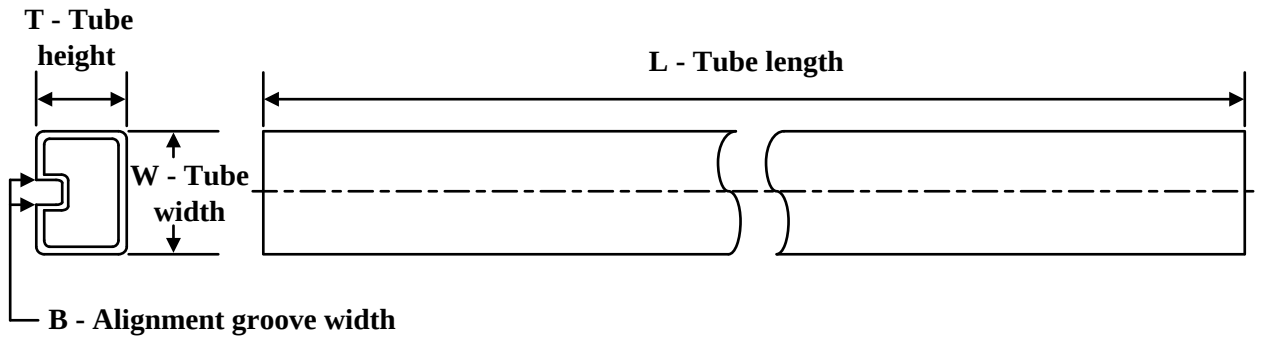
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

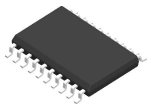
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ACT1284DBR	SSOP	DB	20	2000	356.0	356.0	35.0
SN74ACT1284DWR	SOIC	DW	20	2000	367.0	367.0	45.0
SN74ACT1284NSR	SOP	NS	20	2000	367.0	367.0	45.0
SN74ACT1284PWR	TSSOP	PW	20	2000	356.0	356.0	35.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ACT1284DW	DW	SOIC	20	25	507	12.83	5080	6.6

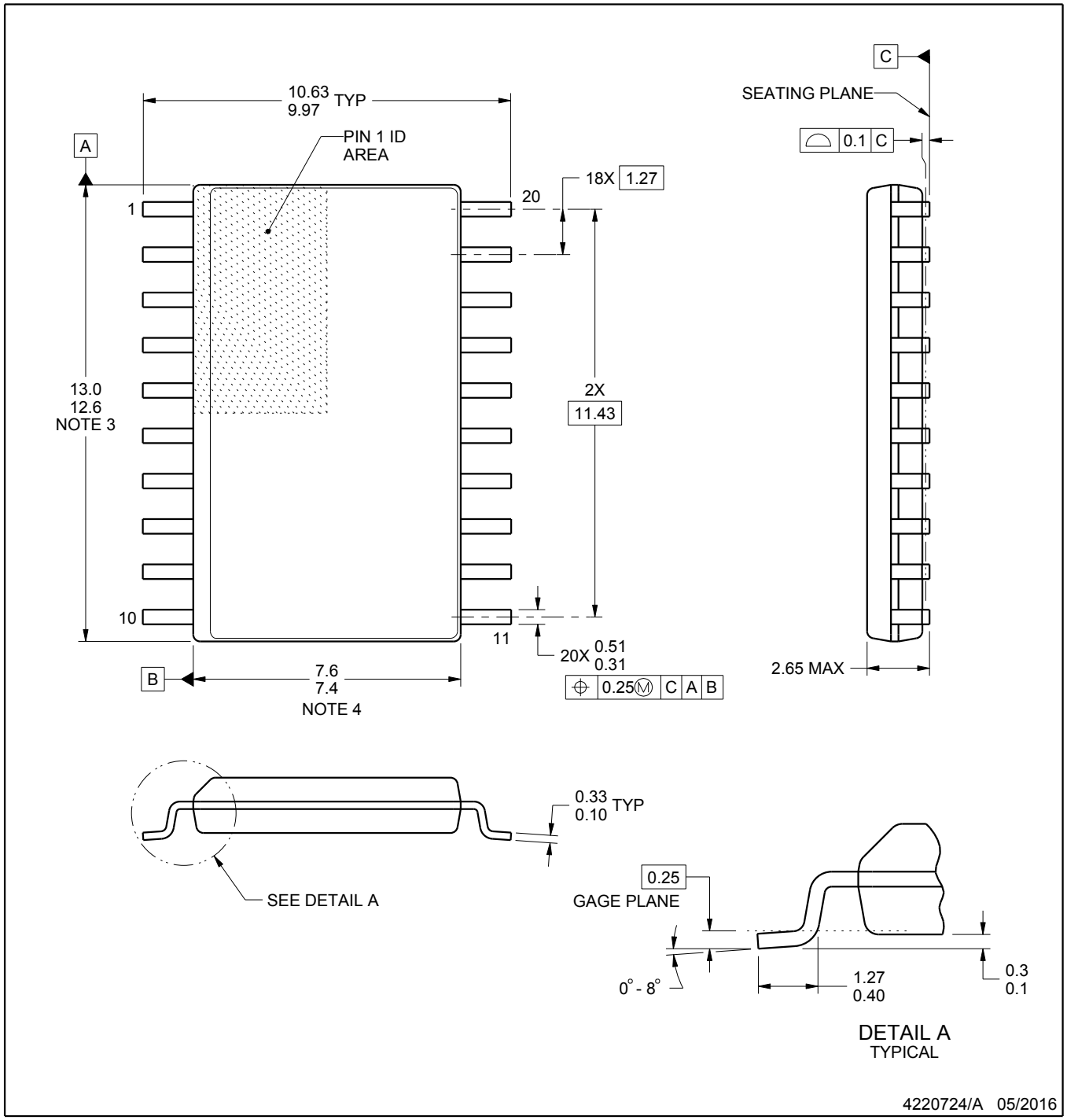


PACKAGE OUTLINE

DW0020A

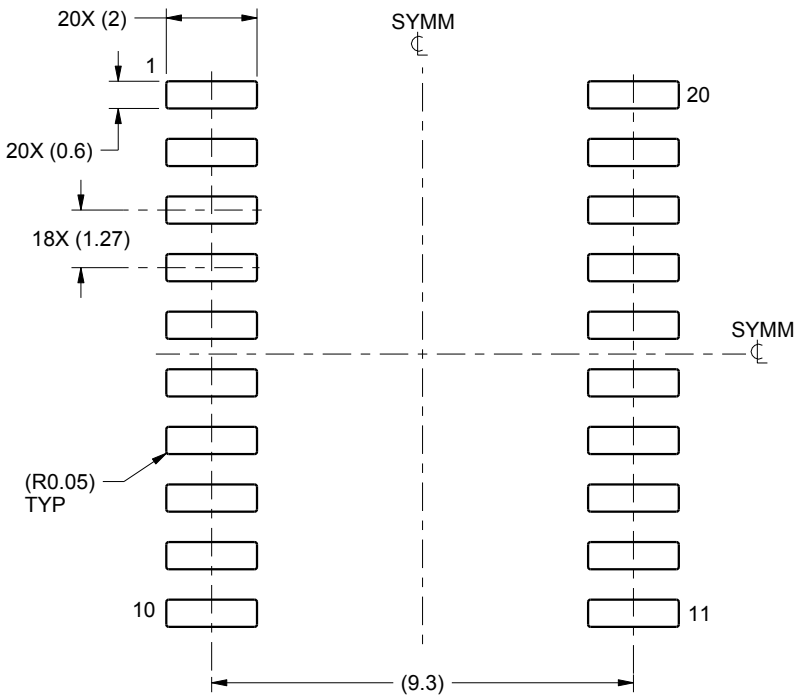
SOIC - 2.65 mm max height

SOIC

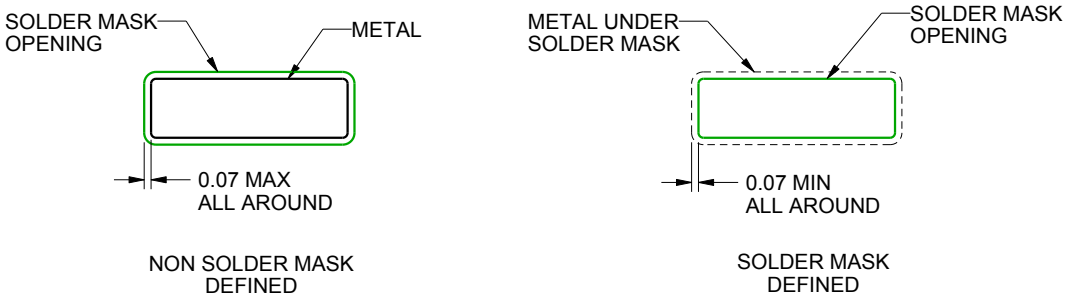


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.



LAND PATTERN EXAMPLE
SCALE:6X

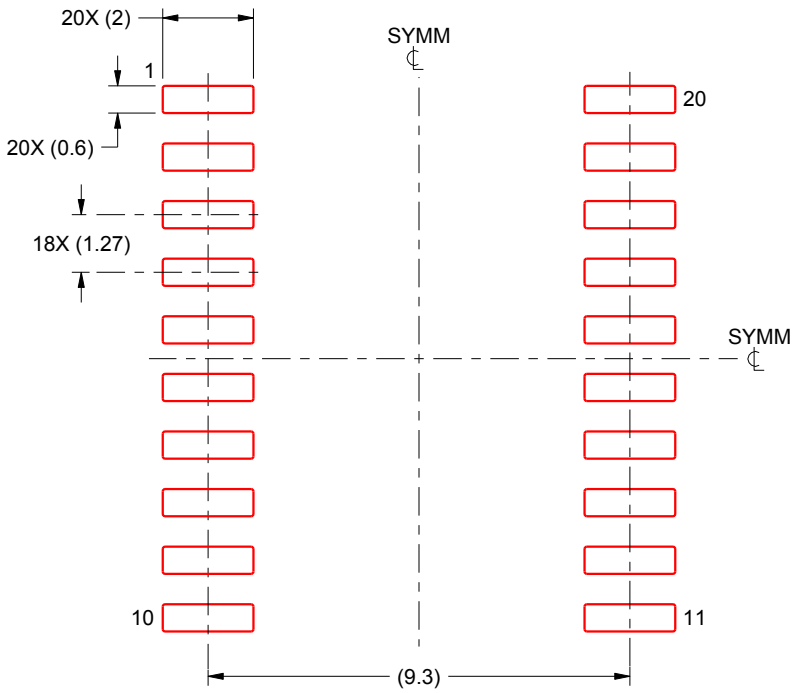


SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

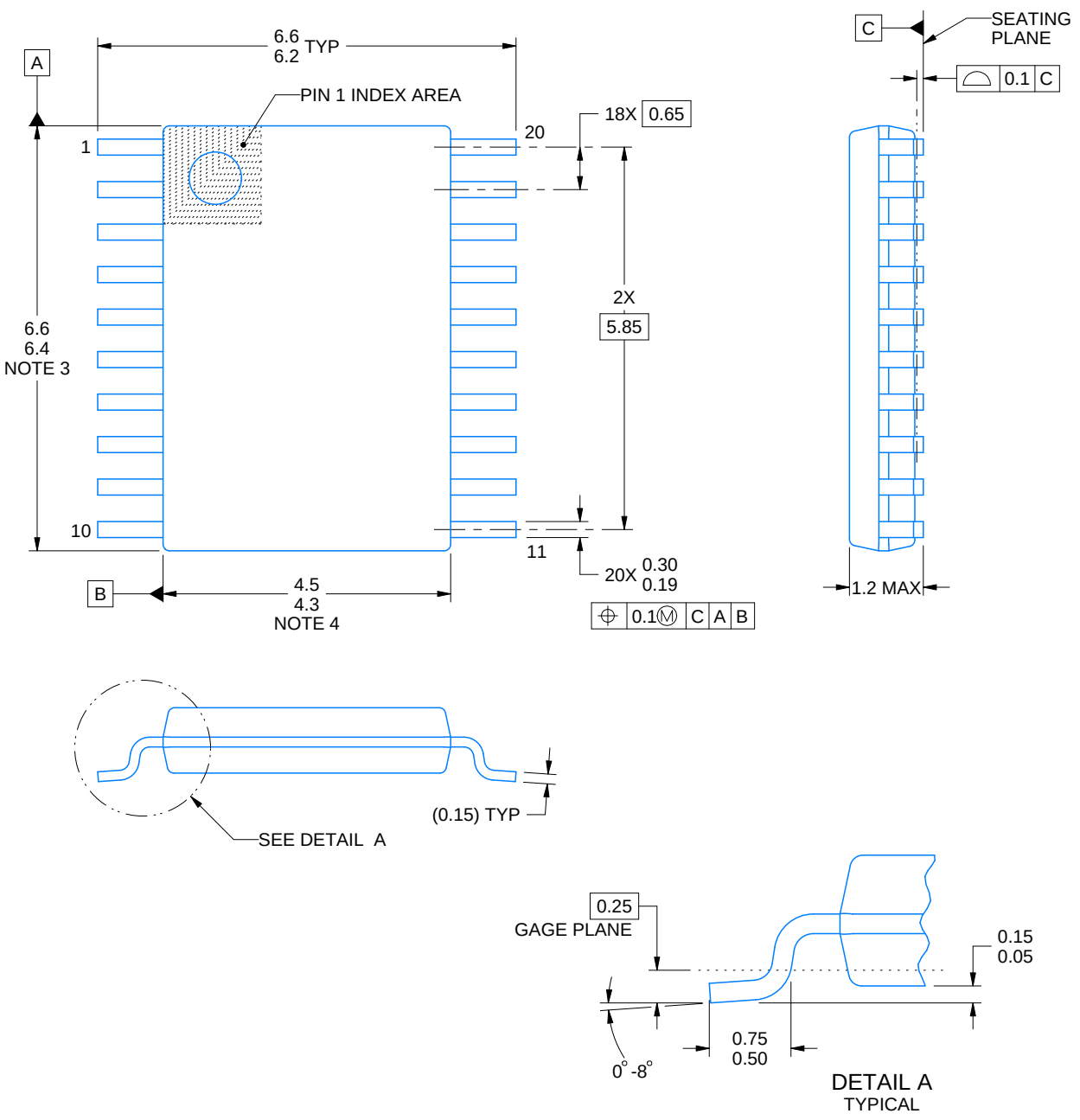
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

PW0020A

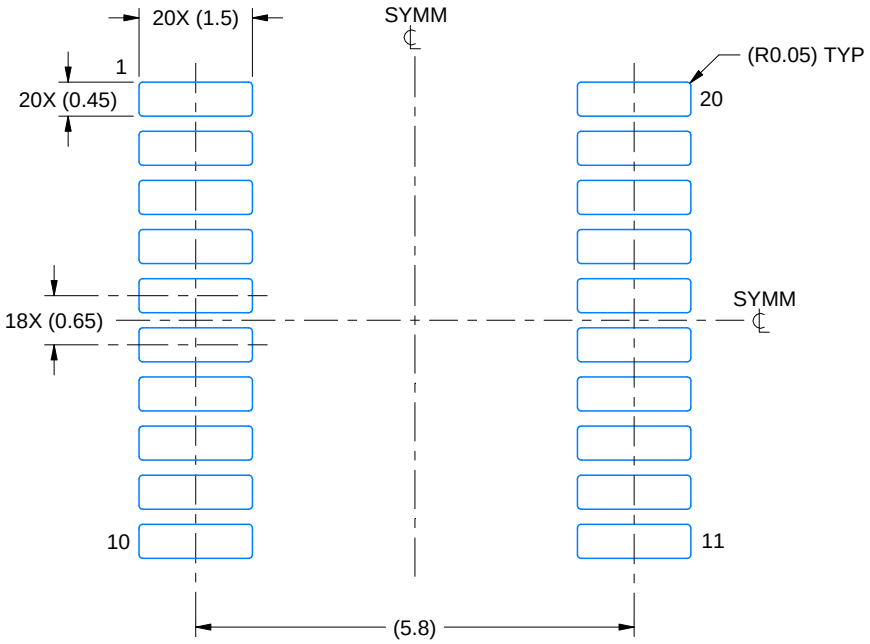
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



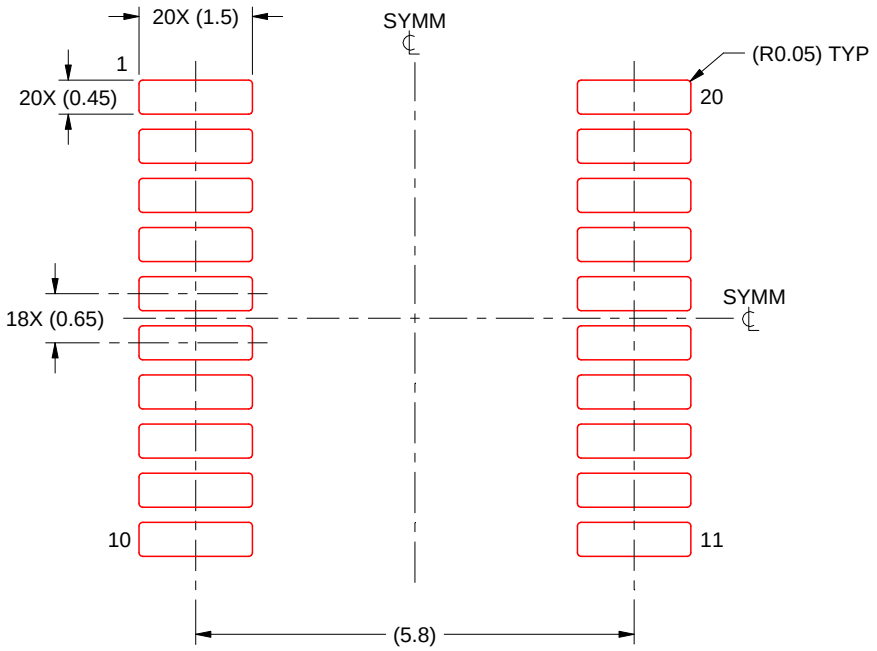
LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

SOLDER MASK DETAILS

4220206/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

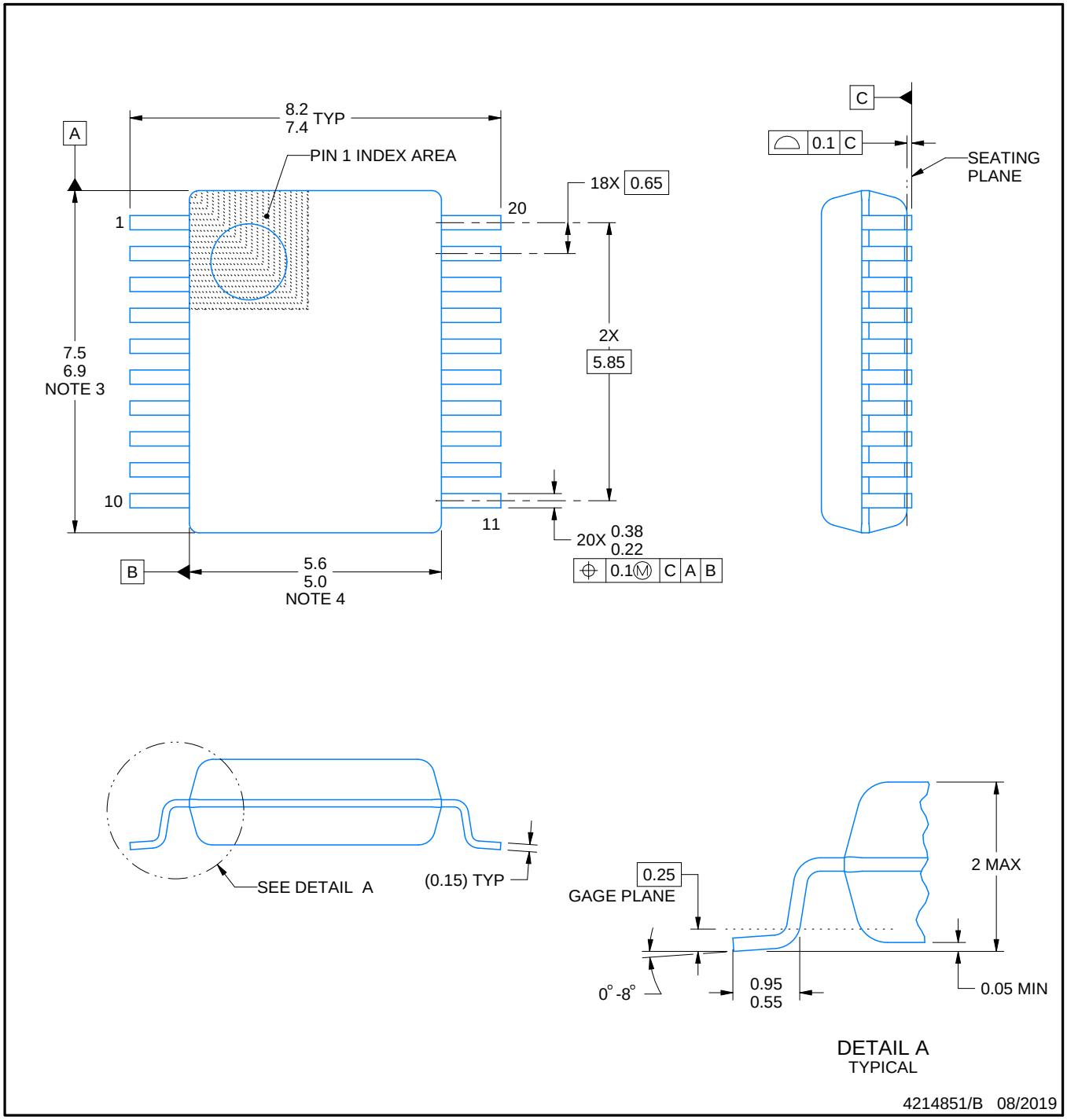
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PACKAGE OUTLINE

DB0020A

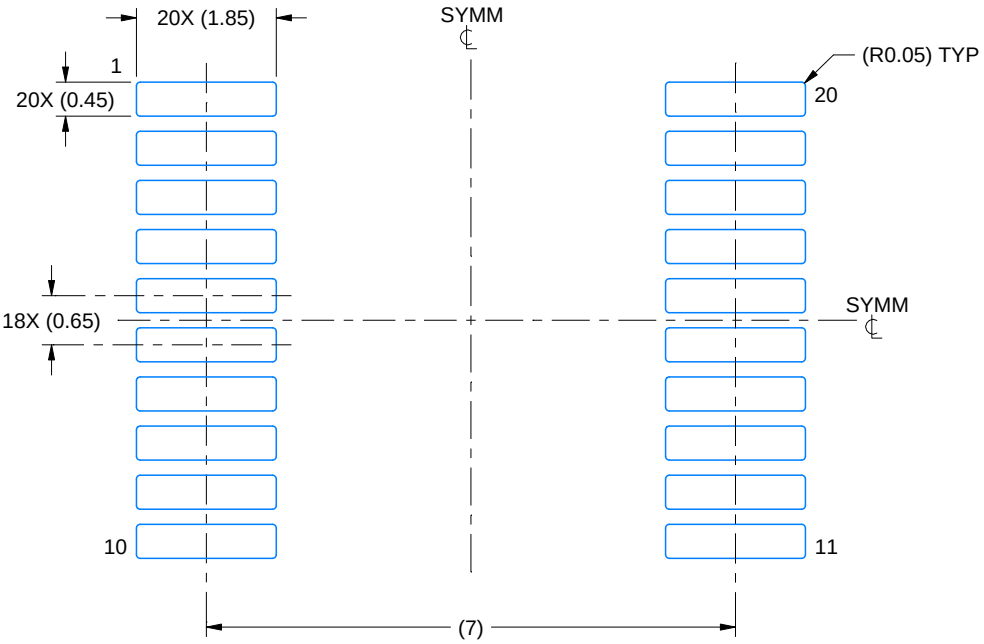
SSOP - 2 mm max height

SMALL OUTLINE PACKAGE

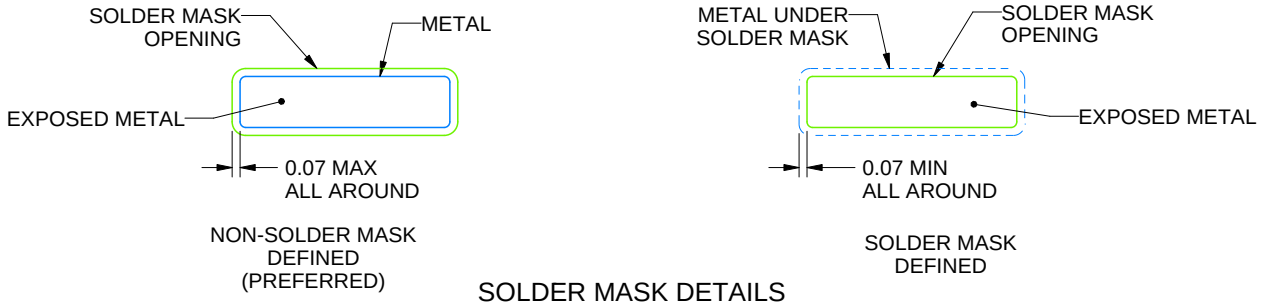


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

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NOTES: (continued)

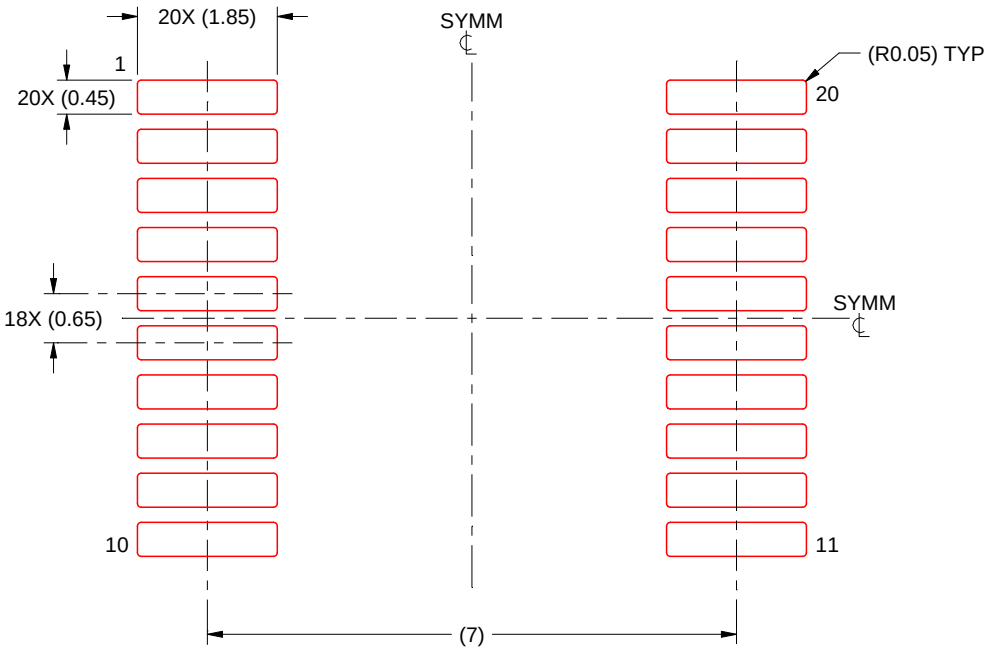
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

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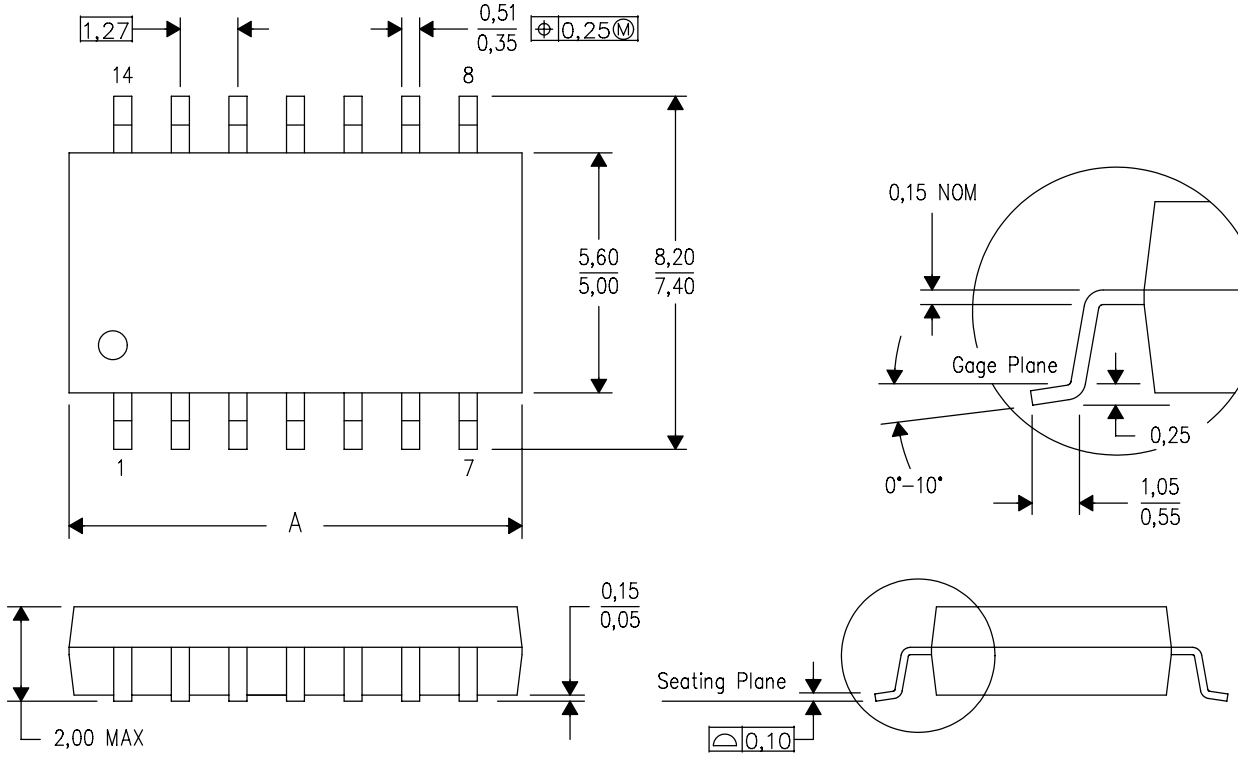
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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